PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT6654946

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SHINYA KAJIYAMA	03/15/2021
YOSHIHIRO HAYASHI	03/12/2021
TADAHIRO NABETA	03/15/2021

RECEIVING PARTY DATA

Name:	HITACHI, LTD.
Street Address:	6-6, MARUNOUCHI 1-CHOME, CHIYODA-KU,
City:	TOKYO
State/Country:	JAPAN
Postal Code:	100-8280

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17229916

CORRESPONDENCE DATA

Fax Number: (703)684-1157

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 703-684-1120
Email: svannarath@mmiplaw.com
Correspondent Name: MATTINGLY & MALUR, PC
Address Line 1: 1800 DIAGONAL ROAD, SUITE 210
Address Line 4: ALEXANDRIA, VIRGINIA 22314

ATTORNEY DOCKET NUMBER:	T&A-13139
NAME OF SUBMITTER:	SHRINATH MALUR
SIGNATURE:	/Shrinath Malur/
DATE SIGNED:	04/14/2021

Total Attachments: 2
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ASSIGNMENT
（譲渡証）

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar ($1.00) or the equivalent thereof, and other good and valuable
consideration paid to me citizen of Japan by HITACHI, LTD.,
a corporation organized under the laws of Japan,
located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan,
receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD.,
its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

TWO-DIMENSIONAL ARRAY ULTRASONIC PROBE AND ADDITION CIRCUIT

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI, LTD.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) （発明者フルネームサイン）	Date Signed （署名日）
1) Shinya Kajiyama (Shinya KAJIYAMA)	March 15, 2021
2) (Yoshihiro HAYASHI)	
3) Tadahiro Nabeta (Tadahiro NABETA)	March 15, 2021
4)	
5)	
6)	
7)	
8)	

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And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	(Shinya KAJIYAMA)	
2)	Yoshihiro Hayashi (Yoshihiro HAYASHI)	March 12, 2021
3)	(Tadahiro NABETA)	
4)		
5)		
6)		
7)		
8)		